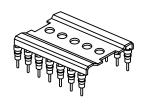




ROW SPACING &

ALC-624-NGG



DIP SOCKET CARRIERS ALC SERIES

Mates with: APO, APA, APH

Aluminum **Carriers** for Direct Soldering to **PC Boards**

Samtec aluminum carriers are available in the most popular DIP lead counts for direct mounting of lead sockets to the printed circuit board. They are ideal for vapor phase, infrared and other high temperature

Low insertion force. six-finger contacts or standard insertion force four-finger contacts are available. Shell styles include ultra-low profile

soldering techniques.

NO. OF CONTACTS Specify from chart below

-3AA -(7.62)				
		Row Space	No. of Contacts	
Γ	-314	(7,62) .300	14	
Γ	-316		16	
Γ	-318		18	
	-320		20	
	-324		24	
	-624	(15,24) .600	24	
L	-628		28	
	-632		32	
L	-640		40	

STYLE OPTION

PLATING OPTION

GG = 30µ" (0,76µm) Gold Contact 10µ" (0,25µm) Gold Shell

GT = 30µ" (0,76µm) Gold Contact, Tin Shell

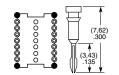
ТΤ = Tin Contact and Shell (Styles –S,–ZS, –L,–M,–N only)

= 10µ" (0,25µm) Gold Contact Tin Shell (Styles -S & -ZS only)

OTHER **OPTION**

= Locking Socket

Requires Style -S, -ZS, or -ZP and .035"±.003" board hole.



Requires GT Plating Option

Lead DIA Accepted = .015" to .022" (0,38mm to 0,56mm) Insertion Depth = .095" to .150" (2.41mm to 3,81mm) Component Part No. = SC-1L1 or EZ-1L1

Low Insertion Force (LIF) Contacts Available.

SPECIFICATIONS

For complete specifications see www.samtec.com?ALC

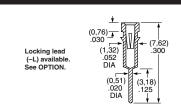
Insulator Material: Carrier Material: Aluminum Contact: BeCu Shell: Brass Shell: Brass
Plating:
Au over 50µ" (1,27µm) Ni
or Sn over 100µ" (2,54µm)
Cu or 50µ" (1,27µm) Ni
Current Rating:1 A
Contact Resistance: 10 m Ω min Insertion Force: Standard = 9 oz (2,50N) avg, 16 oz (4,45N) max Low Insertion Force = 2.5 oz (0,70N) avg, 5.5 oz ,53N) max

Withdrawal Force: Standard = 2.5 oz (0,70N) avg, Standard = 2.5 oz (0,70N) av. 1.5 oz (0,42N) min Low Insertion Force = 2.0 oz (0,56N) avg, 0.35 oz (0,10N) min except Styles ZM & ZN = 2.0 oz (0,56N) avg, 0.5 oz (0,14N) min

Note:

Some sizes, styles and options are non-standard, non-returnable

S = Standard Solder Tail For LIF Specify –ZS



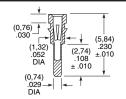
Lead DIA Accepted = .015" to .022" (0,38mm to 0,56mm) Insertion Depth = .095" to .150" (2,41mm to 3,81mm) Style S Component Part No. = SC-191 Style S Component Part No. = EZ-1P1

ZD= Micro Socket **Low Insertion Force**



Lead DIA Accepted = .015" to .022" (0,38mm to 0,56mm) Insertion Depth = .080" to .115" (2,03mm to 3,92mm) Style ZD Component Part No. = EP-101

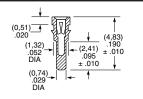
_ = Low Profile, Hollow Leg For LIF Specify -ZL



Lead DIA Accepted = .015" to .020" (0.38mm to 0.51mm) Insertion Depth = .105" to .170" (2,76mm to 4,32mm Style L Component Part No. = SC-3P1 Style ZL Component Part No. = EZ-3P1

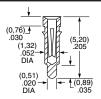
Due to technical progress, all designs, specif

■ Low Profile, Standard Mount For LIF Specify -ZM



Lead DIA Accepted = .016" to .021" (0.41mm to 0.53mm Insertion Depth = .080" to .115" (2,03mm to 2,92,mm)
Style M Component Part No. = SC-4P1
Style ZM Component Part No. = EZ-4P1

-N = Low Profile, Micro Socket For LIF Specify -ZN



Lead DIA Accepted = .016" to .020" (0,41mm to 0,51mm) Insertion Depth = .080" to .150" Style N Component Part No. = SC-5P1 Style ZN Component Part No. = EZ-5P1

ations and components are subject to change without notice ■ WWW.SAMTEC.COM ■